



OPTICAL

THERMALLY
CONDUCTIVE

ELECTRICALLY
CONDUCTIVE

UV & UV
HYBRID

SELECTOR GUIDE

Specialty Epoxies, UV & UV Hybrids

Epoxy Technology's extensive line of optical adhesives is used for bonding, potting, and coating in many applications, most commonly in fiber optics. Our epoxy adhesives are frequently used to bundle optical fibers and bond components in optoelectronic devices.

Selected product listing for EPO-TEK® optical adhesives

Product	Color before/after cure (thin film)	Cure conditions (minimal)	Viscosity @ 23°C (cPs)	Glass transition temperature (°C)	Lap shear strength (psi)	Modulus (psi)	Index of refraction (Nd)	Spectral transmission	Pot life (@ room temp)
301	Clear/colorless	65°C – 1 hour 23°C – 24 hours	@ 100 rpm 100 – 200	≥65	>2,000	436,249	1.5190	≥99% @ 382 – 980nm ≥97% @ 980 – 1640nm	1 – 2 hours
301-2	Clear/colorless	80°C – 3 hours 23°C – 2 days	@ 100 rpm 225 – 425	≥80	>2,000	432,279	1.5318	>99% @ 400 – 1200nm >98% @ 1200 – 1600nm	8 hours
301-2FL	Clear/colorless	80°C – 3 hours 23°C – 3 days	@ 100 rpm 100 – 200	≥45	>2,000	318,685	1.5102	>99% @ 400 – 1000nm >97% @ 1000 – 1600nm	10 hours
302	Clear/colorless	23°C – 2 hours	@ 20 rpm 5,000 – 10,000	≥40	1,756	153,918	1.5442	>85% @ 440 – 900nm >88% @ 900 – 1600nm	10 min
302-3M	Clear/colorless	65°C – 3 hours 23°C – 24 hours	@ 100 rpm 800 – 1,600	≥55	>2,000	456,443	1.5446	>95% @ 460 – 1620nm	1 hour
305	Clear/colorless	65°C – 1 hour 23°C – 24 hours	@ 100 rpm ≤250	≥35	1,880	100,395	1.4763	>95% @ 340nm >98% @ 400-1600nm	1 hour
310M-2	Clear/colorless	65°C – 2 hours 23°C – 24 hours	@ 100 rpm 250 – 325	≤30	678	1,936	1.4947	>98% @ 380 – 1660nm	1.5 hours
320 †	Black/black	65°C – 2 hours 23°C – 24 hours	@ 100 rpm 700 – 1,200	≥55	>2,000	506,751	N/A	<1% @ 300 – 2500nm	1 hour
323LP	Slight yellow/amber	90°C – 30 min	@ 50 rpm 3,500 – 5,000	≥100	>2,000	444,110	1.5704	>90% @ 640 – 800nm >94% @ 820 – 1620nm	24 hours
353ND	Amber/dark red	150°C – 1 min 100°C – 10 min	@ 100 rpm 3,000 – 5,000	≥90	>2,000	508,298	1.5694	>98% @ 800 – 1000nm >95% @ 1100 – 1600nm	≤3 hours
353NDP	Amber/dark red	150°C – 1 min 80°C – 30 min	@ 50 rpm 3,600	≥90	>2,000	320,968	1.569	≥95% @ 1100-1600 nm ≥98% @ 800-1000 nm	≤3 hours
353ND-T †	Tan/dark red	150°C – 1 min 100°C – 10 min	@ 20 rpm 9,000 – 15,000	≥90	1,953	559,120	N/A	N/A	3 hours
354-2	Clear/amber	150°C – 10 min 80°C – 2 hours	@ 20 rpm 7,415	123	1,018	259,762.6	1.5759	>95% @ 600-2100 nm	3 days
360	Light yellow/amber	150°C – 1 min 100°C – 10 min	@ 100 rpm 350 – 550	≥90	>2,000	322,012	1.5345	>97% @ 700 – 1600nm >88% @ 600nm	6 hours
377	Amber/ dark amber	150°C – 1 hour	@ 100 rpm 150 – 300	≥95	1,456	373,622	1.5195	≥90% @ 600nm – 1000nm ≥98% @ 1000 – 1600nm	24 hours
383ND	Amber/dark red	90°C – 30 min	@ 50 rpm 3,500 – 6,000	≥100	>2,000	369,039	1.5715	90% @ 520 – 1600nm	8 hours
OD2002	Cloudy amber/dark amber	150°C – 5 min 100°C – 30 min	@ 5 rpm 24,000 – 42,000	≥140	1,570	263,291	1.5728	>98% @ 800 – 1640nm	4 hours

Note: 23°C denotes RT cure † Thixotropic Paste

EPO-TEK® 301 family

The 301 family of adhesives is clear and colorless. Available in a variety of related formulations for your specific application needs.

Room temperature curing*	301, 301-1, 301-2, 301-2FL, 302, 305, 310M-2
Very low viscosity	301, 301-1, 301-2 & 301-2FL
Low stress	301-2FL, 305, 310M-2
Long pot life	301-2 (8 hrs), 301-2FL (10 hrs)

**Faster curing achieved at higher temperatures, see data sheets for alternate cure schedules*

EPO-TEK® 353ND family

The 353ND Family is one of our most popular, well known adhesive product lines. Variations are most easily characterized by these distinct properties:

Long pot life	323LP (24 hrs) & 383ND (8 hrs)
High tg	OD2002 (high strength, low modulus)
High thixotropy	323LP-T, 353ND-T
UV tacking	HYB-353ND (Refer to UV Hybrid Section)
UV tacking and thixotropic	HYB-353ND-TX2, HYB-353ND-TX3
Additional moisture protection	353NDP



Preferred packaging for EPO-TEK® adhesive products is a single component syringe.

EPO-TEK® syringes offer many advantages:

- Increased reliability and consistency
- Ease of use - no mixing, less waste, lower environmental impact
- Increased productivity - cost effective

THERMALLY CONDUCTIVE

EPO-TEK® thermally conductive, electrically insulating adhesives (TCA) are widely used in many high-tech electronic applications for superior performance & thermal management. Properties range from rigid (providing thermally enhanced circuit protection) to flexible (ideal for CTE mismatches).

Selected product listing for EPO-TEK® thermally conductive adhesives

Product	Cure conditions (minimal)	Viscosity @ 23°C (cPs)	Glass transition temperature (°C)	Die shear strength @ (80 mil x 80 mil)	Modulus (psi)	Thermal conductivity (W/m²K)	Suggested intermittent operating temperature (°C)	Pot life (@ room temp)
930-4	150°C – 10 min 80°C – 6 hours	@ 20 rpm 12,000 – 17,000	≥90	≥15kg / 5,334psi	607,651	1.70	<325	1 day
H67-MP†	150°C – 1 hour	@ 1 rpm 300,000 – 400,000	≥90	≥20kg / 7,112psi	641,860	0.50	<300	28 days
H70E	150°C – 5 min 80°C – 90 min	@ 50 rpm 4,000 – 7,000	≥80	≥10kg / 3,556psi	787,350	0.90	<300	56 hours
H70E-2	150°C – 5 min 80°C – 90 min	@ 20 rpm 9,000 – 15,000	≥80	≥5kg / 1,778psi	1,214,415	1.00	<300	2 days
H74	150°C – 5 min 100°C – 20 min	@ 5 rpm 45,000 – 65,000	≥100	≥15kg / 5,334psi	860,430	1.30	<350	2 hours
H77	150°C – 1 hour 100°C – 1 hour+ { step 120°C – 2 hours	@ 20 rpm 6,000 – 12,000	≥80	≥5kg / 1,778psi	950,693	0.70	<350	6 hours
T6065	180°C – 1 hour	@ 2.5 rpm 180°C – 1 hour	≥100	≥20kg / 7,112psi	816,394	0.80	<300	28 days
T7109	150°C – 10 min 80°C – 8 hours	@ 20 rpm 14,000 – 20,000	≥45	≥15kg / 5,334psi	258,593	0.70	<300	4 hours
T7109-19	80°C – 2 hours 23°C – 2 days	@ 5 rpm 40,000 – 70,000	≤40	≥5kg / 1,778psi	29,931	1.30	<250	2 hours
T7110	80°C – 2 hours 23°C – 3 days	@ 100 rpm 1,400 – 2,200	≥40	≥10kg / 3,556psi	789,250	1.00	<250	3.5 hours
T905BN-3	80°C – 2 hours	@ 50 rpm 2,000 – 7,000	≥40	≥10kg / 3,556psi	721,520	2.00	<300	3 hours
TJ2139-LH BLACK	200°C – 5 min 140°C – 40 min	@ 10 rpm 25,000-35,000	≥100	≥30 Kg /10,668 psi	631,753	0.50	<350	2.5 days
TV2001	160°C – 5 min 120°C – 30 min	@ 20 rpm 10,000 – 20,000	≥15	≥15kg / 5,334psi	16,271	0.40	<325	2 days
TZ101	150°C – 1 hour	@ 10 rpm 24,000 – 30,000	≥40	≥10kg / 3,556psi	513,778	0.90	<275	28 days

Note: 23°C denotes RT cure † MIL-STD 883/5011 certified

High thermal management

EPO-TEK® products are unparalleled in their performance for effectively removing heat, providing increased dielectric strength and protecting circuits from hostile environments.

930-4*

- Long pot life
- Hi-Rel (automobile grade)
- Excellent adhesion to diverse substrates
- Small particle size ($\leq 20\mu\text{m}$)

H74*

- Thixotropic paste
- NASA low outgassing
- Superior chemical & moisture resistance
- Medium to average particle size ($\leq 50\mu\text{m}$)

H70E*

- Long pot life
- Semi-conductor die attach
- Precision dispensing
- NASA low outgassing

Low stress/flex/compliant

This grouping was specially formulated for stress relieving applications such as: large area bonding, potting and thermal cycling.

T7109*

- Syringe dispensing
- Thermal cycling resistance
- Photonics packaging

TZ101*

- Low tg & modulus
- Long pot life
- High strength
- One component

TV2001

- Very low tg
- Low modulus
- High strength
- Excellent adhesion

Low temperature cure

T7109-19*

- Low tg
- Low modulus
- High thermal conductivity
- Room temperature curable

T7110*

- Low viscosity, self-leveling
- Room temperature curable
- Large-scale potting

T905BN-3

- Ideal for large volume
- Potting & casting
- Large particle size ($< 300\mu\text{m}$)
- Tamper-proof

**Variations of these formulations available*



Preferred packaging for EPO-TEK® adhesive products is a single component syringe.

EPO-TEK® syringes offer many advantages:

- Increased reliability and consistency
- Ease of use - no mixing, less waste, lower environmental impact
- Increased productivity - cost effective

ELECTRICALLY CONDUCTIVE

Epoxy Technology offers a comprehensive range of epoxy adhesives that are electrically conductive; our broad range of electrically conductive adhesives (ECAs) allow users to select the optimal adhesive for their specific application based on the best combination of physical, electrical, thermal and mechanical properties.

Selected product listing for EPO-TEK® electrically conductive adhesives

Product	Cure conditions (minimal)	Viscosity @ 23°C (cPs)	Glass transition temperature (°C)	Die shear strength @ RT (80 mil x 80 mil)	Volume Resistivity (ohm-cm)	Thermal conductivity (W/m²K)	Suggested intermittent operating temperature (°C)	Modulus (psi)	Pot life (@ room temp)
E2101	150°C – 1 hour	@ 20 rpm 15,000 – 18,000	≥90	>5kg / 1,778psi	≤0.0005	2.50	<300	1,052,430	5 days
EJ2108	150°C – 1 hour 80°C – 2 hour 23°C – 3 days	@ 10 rpm 8,000 – 20,000	≥30	≥5kg / 1,778psi	≤0.0001	4.00	<175	2,553	1 hour
EJ2189-LV	150°C – 1 hour 23°C – 3 days	@ 1 rpm 25,000 – 45,000	≥40	≥10kg / 3,556psi	≤0.0005	2.50	<250	213,672	4 hours
EJ2312	150°C – 1 hour 23°C – 24 hours	@ 1 rpm 58,822	N/A	≥5kg / 1,778psi	≤0.0005	5.6	<250	N/A	90 mins
EK1000†	150°C – 1 hour Step: 150°C – 1 hour + 200°C – 1 hour	@ 100 rpm 1,800 – 3,600	≥80	>10kg / 3,556psi	≤0.0007	26.3 (two-step cure)	<300	273,528	2 weeks
H20E†	150°C – 5 min 80°C – 3 hours	@ 100 rpm 2,200 – 3,200	≥80	>10kg / 3,556psi	≤0.0004	29.0 (TO-18)	<300	808,700	2.5 days
H20E-PFC	175°C – 45 sec 80°C – 3 hours	@ 100 rpm 3,000 – 4,000	≥80	≥5kg / 1,778psi	≤0.0004	3.20	<325	921,254	3 days
H20S	150°C – 5 min 80°C – 90min	@ 100 rpm 1,800 – 2,800	≥80	≥5kg / 1,778psi	<0.0005	3.3	<300	339,720	3 days
H22	150°C – 5 min 100°C – 20min	@ 10 rpm 17,000 – 30,000	≥100	≥5kg / 1,778psi	≤0.005	0.90	<350	540,120	16 hours
H35-175MP*	180°C – 1 hour 165°C – 1.5 hours	@ 10 rpm 22,000 – 28,000	≥100	≥10kg / 3,556psi	≤0.0005	1.50	<300	1,106,623	28 days
H37-MP*	150°C – 1 hour	@ 10 rpm 22,000 – 26,000	≥90	≥10kg / 3,556psi	≤0.0005	1.59	<300	727,680	28 days

Certified to MIL-STD 883/5011 (MP) † H20E and EK1000 are also available in "MP" grade

Room temperature curing

EJ2189	Most robust room temperature formulation with superior adhesion
EJ2189-LV	Lower viscosity version of EJ2189 (viscosity is similar to H20E)
EJ2108	Room temperature cure with some flexibility
EJ2312	Fastest room temperature cure for ECA

Highest thermal and electrical conductivity

Innovative, "Next Generation" ECA's with unsurpassed performance & exceptional thermal management

EK1000	Single component with superior thermal conductivity
EK2000	Two component version of EK1000
EK1000-1	Extended dry time version of EK1000 (<7 days vs. ≤1day)
EK1000-1-D	Enhanced dispensability version of EK1000-1

Low stress/flex

EJ2108	Medium viscosity, thixotropic paste with low modulus and low temp curable (<80°C)
EJ2118-2	Medium viscosity, thixotropic paste with excellent thermal conductivity

Industry standard ECA products

H20E	Proven reliability for over 50 years
H20E-FC	Fastest curing version
H20E-PFC	Optimal rheology for screen/stencil printing
H20S	Smooth consistency, designed for die stamping & dispensing



EK1000-MP
Highest thermal conductivity

H20E-MP
Industry standard

H35-175MP
Small chip & SMD bonding

H35-175MPLV
Lower viscosity version

H35-175MPT
Higher thixotropic version

H37-MP
Lower stress and lower cure temperature version of H35-175MP

H37MP-2
Slightly higher viscosity

H37-MPT
Higher thixotropic version

UV ADHESIVES

EPO-TEK® offers an exclusive line of high performance UV curing adhesives based on both epoxy as well as acrylate systems. Our unique UV formulations provide superior performance with short cure times for a wide variety of applications. Many of our novel epoxy/UV formulations can be further enhanced by thermal post curing.

EPOXY-BASED > **Thermal post cure** - increases the degree of cross-link; enhancing performance

UV + thermal post cure (typically 80-150°C) for enhanced performance

Product	Cure conditions (minimal)	Viscosity @ 23°C (cPs)	Glass transition temperature (°C)	Hardness	Index of refraction Nd*	Spectral transmission	Performance features
OG116**	100mW/cm2 @ 240 – 365nm for > 30 sec	@ 2.5 rpm 80,000 – 105,000	≥135	80D	1.5892	89% @ 400nm ≥98% @ 560 – 1660nm	Higher viscosity version of OG116-31, good chemical resistance, high Tg & refractive index, very high strength
OG116-31	100mW/cm2 @ 240 – 365nm for > 30 sec	@ 10 rpm 20,000 – 30,000	≥115	83D	1.5842	≥92% @ 500nm ≥96% @ 660 – 1640nm	High speed dispensability, IC glob top, good chemical resistance, high Tg and high index
OG142-87	100mW/cm2 @ 240 – 365nm for > 30 sec	@ 100 rpm 250 – 600	≥100	82D	1.5058	>97% @ 580 – 1660nm	Low viscosity, excellent bond strength and optical clarity, non-yellow
OG142-95	100 mW/cm2 @ 240 – 365nm for > 30 sec	@ 100 rpm 300 – 700	≥100	82D	1.5123	≥97% @ 580 – 1660nm	Improved wetting version of OG142-87
OG142-112	100mW/cm2 @ 240 – 365nm for > 30 sec	@ 100 rpm 1,200 – 1,700	≥90	83D	1.5560	>97% @ 500 – 1660nm	Medium viscosity, high moisture resistance, exceptional bond strength
OG159-2	100mW/cm2 @ 240 – 365nm for > 30 sec	@ 2.5 rpm 100,000 – 140,000	≥130	69D	1.5715	≥98% @ 580 – 2000nm	Thixotropic, contains 1 mil glass beads, excellent moisture resistance
UJ1190	100mW/cm2 @ 240 – 365nm for > 60 sec	@ 100 rpm 501	100	80D	1.4993	≥80% @ 380 – 2440nm ≥94% @ 520 – 1560nm	Low viscosity, good for thick sections
UD1355	100mW/cm2 @ 240 – 365nm for > 90 sec	@ 100 rpm 447	36	77D	1.4925	≥96% @ 800 – 2200nm ≥99% @ 360 – 780nm	Optically clear, low viscosity, resists discoloration during solder reflow

* Cured index measured at 589nm ** NASA ASTM E595 Low Outgassing

UV + thermal post cure (typically 80-150°C) for shadow curing <5mm shadow cure with proper thermal care

Product	Cure conditions (minimal)	Viscosity @ 23°C (cPs)	Glass transition temperature (°C)	Hardness	Index of refraction Nd*	Spectral transmission	Performance features
†OG198-54	100mW/cm2 @ 240 – 365nm for > 30 sec	@ 100 rpm 200 – 450	≥115	86D	1.5256	≥97% @ 460 – 1680nm	Low viscosity, high Tg, excellent bond strength
†† OG198-55	100mW/cm2 @ 240 – 365nm for > 30 sec	@ 100 rpm 1,200 – 2,000	≥120	85D	1.5196	≥97% @ 560 – 1680nm	Highly thixotropic, non-flowing gel with high strength and high Tg

* Cured index measured at 589nm † 150°C/1 hour to cure shadowed areas optional ** NASA ASTM E595 Low Outgassing

EPOXY-BASED (continued)

UV cure only							
Product	Cure conditions (minimal)	Viscosity @ 23°C (cPs)	Glass transition temperature (°C)	Hardness	Index of refraction Nd*	Spectral transmission	Performance features
OG133-7	100mW/cm ² @ 240-365nm for > 2 min	@ 100 rpm 150 – 450	≤10	81A	1.5060 [†]	≥90% @ 440 – 580nm ≥96% @ 800 – 1600nm	Low viscosity, flexible, high flow version of OG133-8
OG133-8	100mW/cm ² @ 240-365nm for > 90 secs	@ 100 rpm 1,000 – 1,500	≤10	65A	1.5244	≥90% @ 580 – 800nm ≥95% @ 820 – 1660nm	Thixotropic, low Tg & hardness, excellent flexibility
OG142	100mW/cm ² @ 240 – 365nm for > 30 sec	@ 20 rpm 9,000 – 15,000	≥95	86D	1.5809	≥92% @ 440 – 620nm ≥97% @ 660 – 1640nm	Medium viscosity, high strength, moisture resistance
OG154-1	100mW/cm ² @ 240 – 365nm for > 30 sec	@ 5 rpm 26,000 – 34,000	128	80D	1.5692	97% @ 500 – 1660nm	High viscosity, high Tg, low modulus
* Cured index measured at 589nm † Uncured							

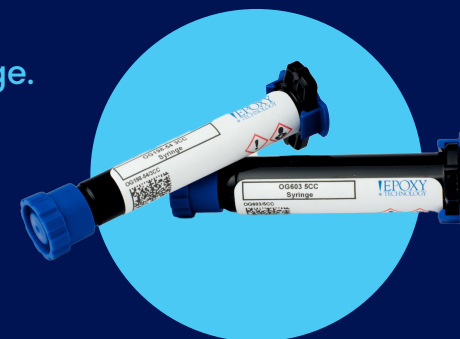
ACRYLATE-BASED

UV cure only							
Product	Cure conditions (minimal)	Viscosity @ 23°C (cPs)	Glass transition temperature (°C)	Hardness	Index of refraction Nd*	Spectral transmission	Performance features
OG603	100mW/cm ² @ 240 – 365nm for > 5 sec	@ 100 rpm 150 – 250	≥70	84D	1.5037	≥98% @ 420 – 1600nm	Low viscosity, fast cure
* Cured index measured at 589nm							

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- Increased reliability and consistency
- Ease of use – no mixing, less waste, lower environmental impact
- Increased productivity – cost effective



UV HYBRID

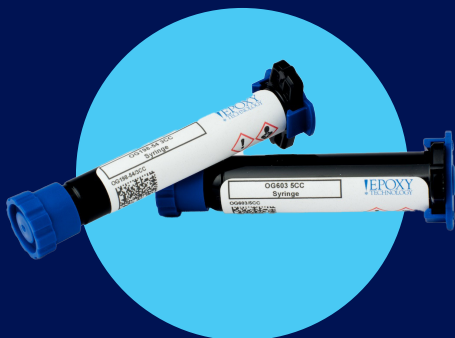
Epoxy Technology has developed a line of unique epoxy-based, UV Hybrid chemistry adhesives. These state-of-the-art formulations allow for improved handling and process control by utilizing both UV and thermal curing. Tacking can be done in seconds, followed up by heat; giving both speed and strength to the process.

Current product listing for EPO-TEK® UV hybrid adhesives

Product	Description	Viscosity	Pot life	Tg (°C)	Cure condition	Degradation temperature (°C)	Weight loss @ 200°C	Die shear	Spectral transmission	*Index of refraction
HYB-353ND-LV	Low viscosity, fast tack	800 – 2,000 cPs @100 rpm	<20 hrs	≥80	UV 10 sec @ 100mW/cm2 +150°C/30min	400	0.08%	≥15kg / 5,334psi	≥95% @ 1100 –1600nm ≥98% @ 800 –1000nm	1.5215
HYB-353ND	Viscosity match of 353ND	3,000 – 7,000 cPs @10 rpm	<2 hrs	≥100	UV 20 sec @ 100mW/cm2 @ + 150°C/30 min	400	0.06%	≥20kg / 7,112psi	≥95% @ 1100 –1600nm ≥98% @ 800 –1000nm	1.5259
HYB-353ND-HV	Higher viscosity version	9,000 – 20,000 cPs @10 rpm	2 hrs	≥100	UV 10 sec @ 100mW/cm2 @ + 150°C/30 min	388	0.03%	≥25kg / 8,890psi	≥95% @ 1100 –1600nm ≥98% @ 800 –1000nm	1.5545
HYB-353ND-TX2	Thixo version TI = 1.7	17,000 – 35,000 cPs @10 rpm	<2 days	≥90	UV 10 sec @ 100mW/cm2 +150°C/30min	410	0.05%	≥15kg / 5,334psi	≥95% @ 1100 –1600nm ≥98% @ 800 –1000nm	1.5457
HYB-353ND-TX3**	Thixo version TI = 1.3	25,000 – 41,000 cPs @10 rpm	<3 days	≥80	UV 10 sec @ 100mW/cm2 +150°C/30min	399	0.19%	≥15kg / 5,334psi	≥95% @ 1100 –1600nm ≥98% @ 800 –1000nm	1.5456
* uncured at 589nm ** NASA ASTM E595 Low Outgassing Lower temperature cures, (80°C) are possible depending upon application										

Benefits of a UV hybrid

- Overall process improvement
- Lower stress and less shrinkage
- Easier handling
- Tack free in seconds
- Increased thru-put on expensive alignment machines
- 85°C/85%RH resistance, comparable to 353ND



UV hybrid development

Additional UV hybrid products are in development and testing; these include room temperature cure, thermally, and electrically conductive hybrids.

Contact our Adhesives Experts at techserv@epotek.com for more information on our latest product offerings.

EPO-TEK® specialty adhesive products + advanced packaging techniques = **premium adhesive performance**

Epoxy Technology, A Meridian Adhesives Group Company, is a global leader in formulating, manufacturing and packaging specialty adhesives. We have packaging facilities in North America, Europe and Asia.

Our specialty formulated adhesives are packaged with meticulous attention to specifications in the following packaging options:

Premixed
and frozen
(PMF)
syringes

Room
temperature
stabilized
syringes

Bi-paks

Why use EPO-TEK® packaged adhesives?

- **Increased Reliability/Consistency/Uniformity**
Precise Mix Ratio, Lot to Lot
- **Cost Effective**
Time Saving in Preparation of Material, Increased Productivity
- **Ease of Use**
Convenient, No Measuring, No Mixing, Ready to Use, Stress-Free



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Established in 1966, Epoxy Technology is a global leader in adhesives, including specialty optical, thermally conductive (TCA), electrically conductive (ECA), and UV/UV hybrid systems. Additionally, we offer an extensive line of tested and certified biocompatible, medical device-grade adhesives, known as our "MED" line.

In 2018, ETI became part of the Meridian Adhesives Group, a full-service global adhesive solutions provider. As part of Meridian's Electronics Division, Epoxy Technology works closely with Epoxy Technology Europe, Epoxies, Etc., and Pacific Adhesives Systems. Together, the Electronics Division delivers high-impact solutions to key global markets, including datacom, telecom, medical, consumer,

and automotive—supporting AI-driven and other advanced optoelectronic and electronic applications. Our high-performance materials are used in some of the most demanding and complex applications, and we are trusted partners of organizations worldwide.



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